

## -20V P-Channel Enhancement Mode MOSFET

### Description

The AP2307AI uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

### General Features

$V_{DS} = -20V$   $I_D = -7A$

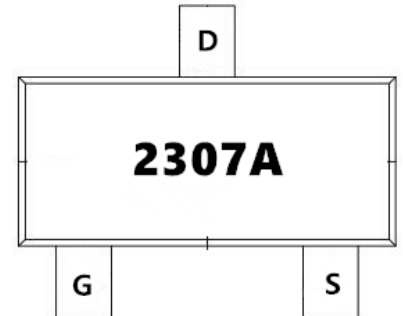
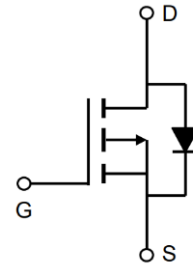
$R_{DS(ON)} < 25m\Omega$  @  $V_{GS} = -4.5V$  (Type: 20m $\Omega$ )

### Application

Quick charge

electronic cigarette

Uninterruptible power supply



### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP2307AI	SOT23L	2307A	3000

### Absolute Maximum Ratings ( $T_A = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-20	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -4.5V^1$	-7	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ -4.5V^1$	-4.8	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-23.8	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation <sup>3</sup>	2	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>	62.5	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	80	$^\circ C/W$

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### Electrical Characteristics (T<sub>J</sub>=25°C, unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
V(BR)DSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> = -250μA	-20	-22	-	V
IDSS	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -20V, V <sub>GS</sub> =0V,	-	-	-1	μA
IGSS	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±12V	-	-	±100	nA
VGS(th)	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> = -250μA	-0.5	-0.7	-1.2	V
RDS(on)	Static Drain-Source on-Resistance note2	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -6A	-	20	25	mΩ
		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -5A	-	28	35	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = -10V, V <sub>GS</sub> =0V, f=1.0MHz	-	2000	-	pF
C <sub>oss</sub>	Output Capacitance		-	242	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	231	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = -10V, I <sub>D</sub> = -3A, V <sub>GS</sub> = -4.5V	-	15.3	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	2.2	-	nC
Q <sub>gd</sub>	Gate-Drain("Miller") Charge		-	4.4	-	nC
td(on)	Turn-on Delay Time	V <sub>DD</sub> = -10V, I <sub>D</sub> = -7A, V <sub>GS</sub> = -4.5V, R <sub>GEN</sub> =2.5Ω	-	10	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	31	-	ns
td(off)	Turn-off Delay Time		-	28	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	8	-	ns
IS	Maximum Continuous Drain to Source Diode Forward Current		-	-	-7	A
ISM	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-28	A
VSD	Drain to Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> = -7A	-	-0.8	-1.2	V

#### Note :

- 1、 The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width ≅ 300us , duty cycle ≅ 2%
- 3、 The power dissipation is limited by 150°C junction temperature
- 4、 The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

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### Typical Characteristics

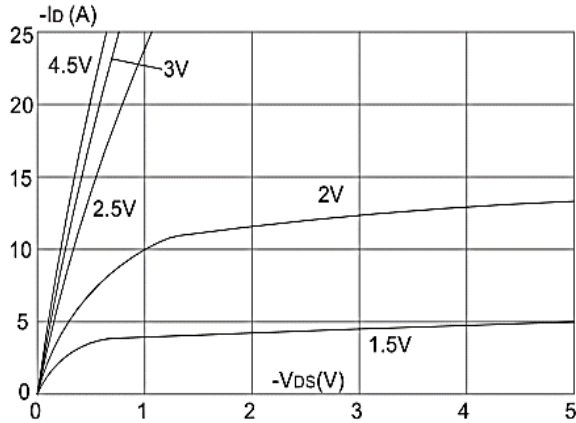


Figure 1: Output Characteristics

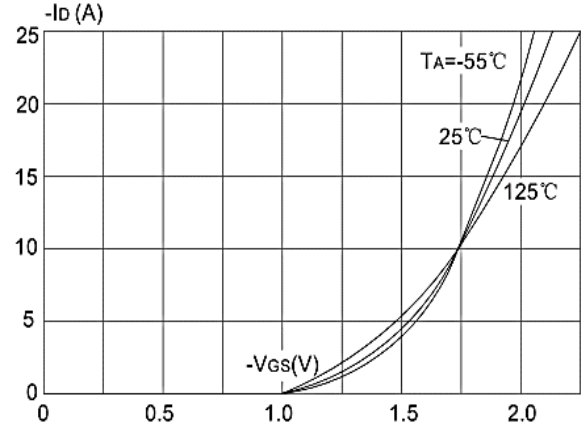


Figure 2: Typical Transfer Characteristics

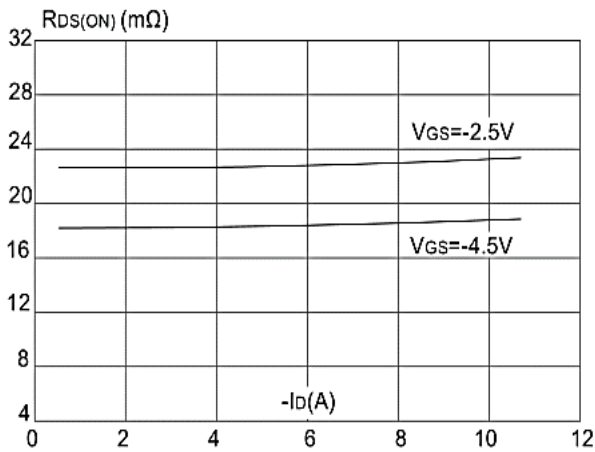


Figure 3: On-resistance vs. Drain Current

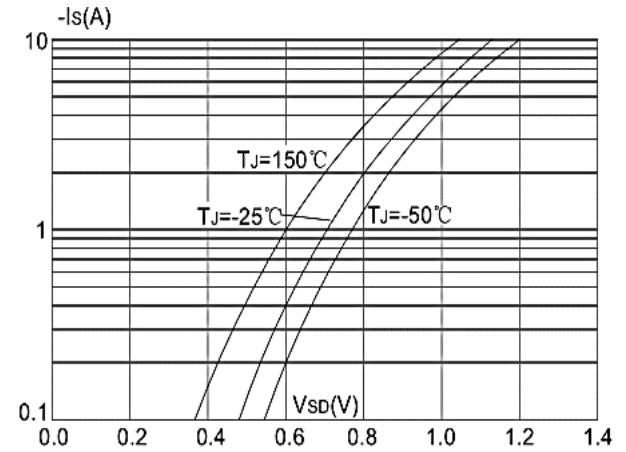


Figure 4: Body Diode Characteristics

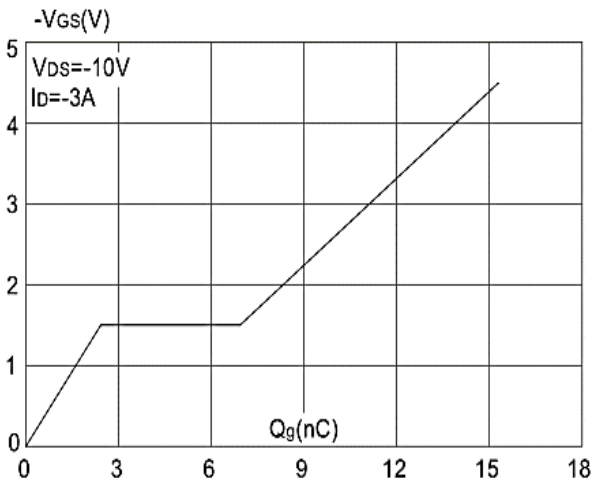


Figure 5: Gate Charge Characteristics

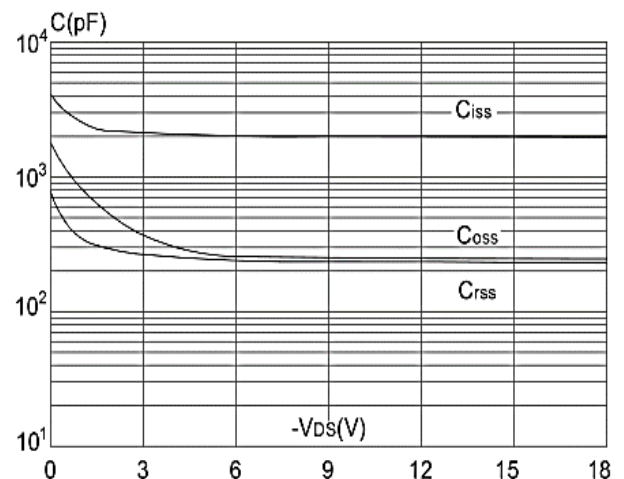
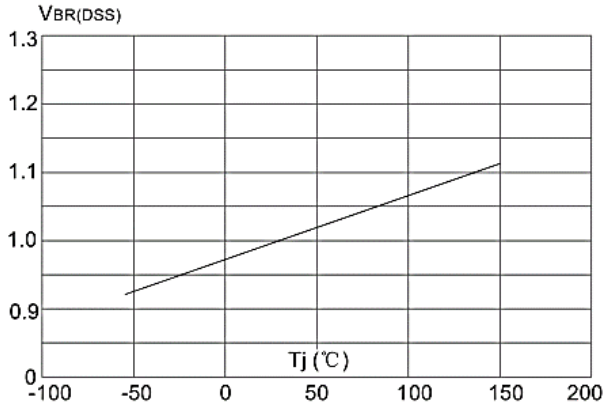
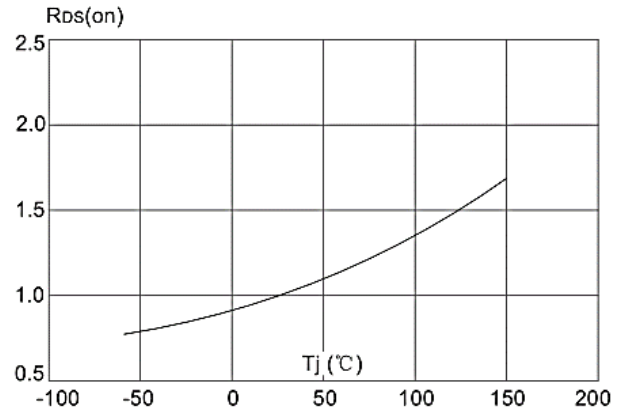


Figure 6: Capacitance Characteristics

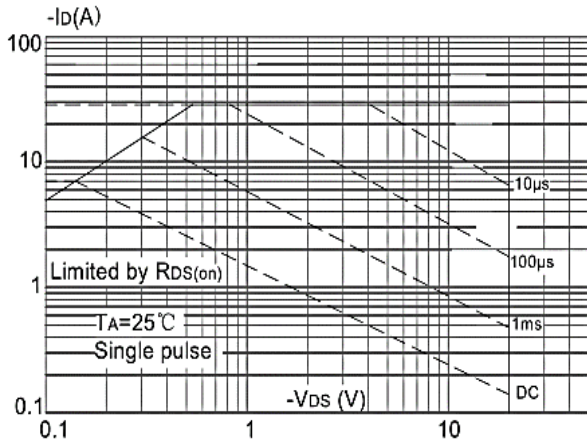
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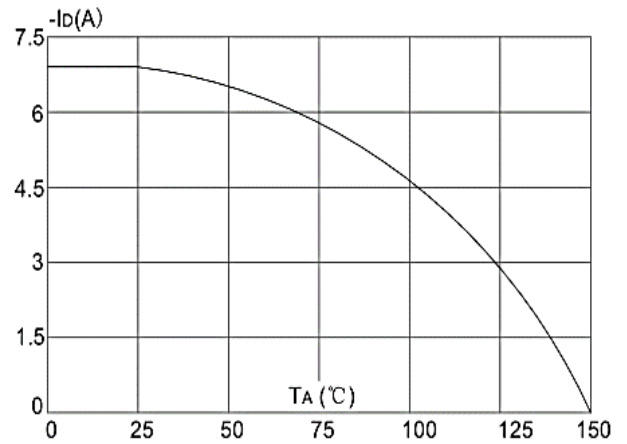
**Figure 7: Normalized Breakdown Voltage vs. Junction Temperature**



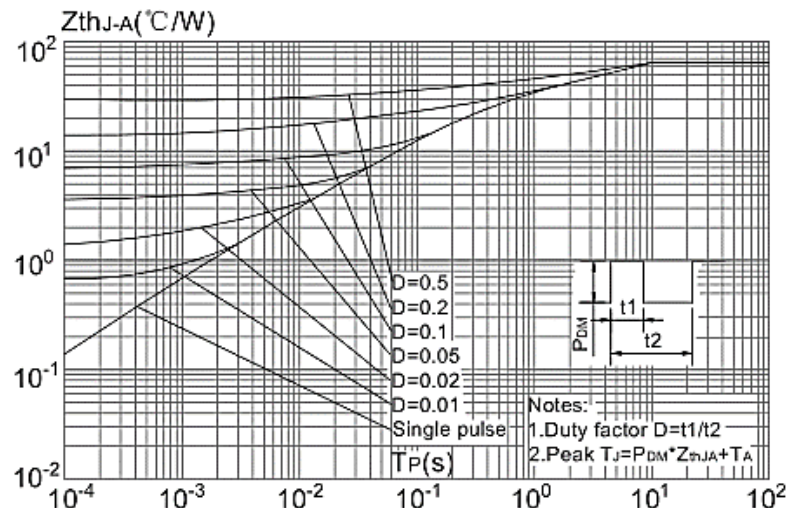
**Figure 8: Normalized on Resistance vs. Junction Temperature**



**Figure 9: Maximum Safe Operating Area vs. Case Temperature**

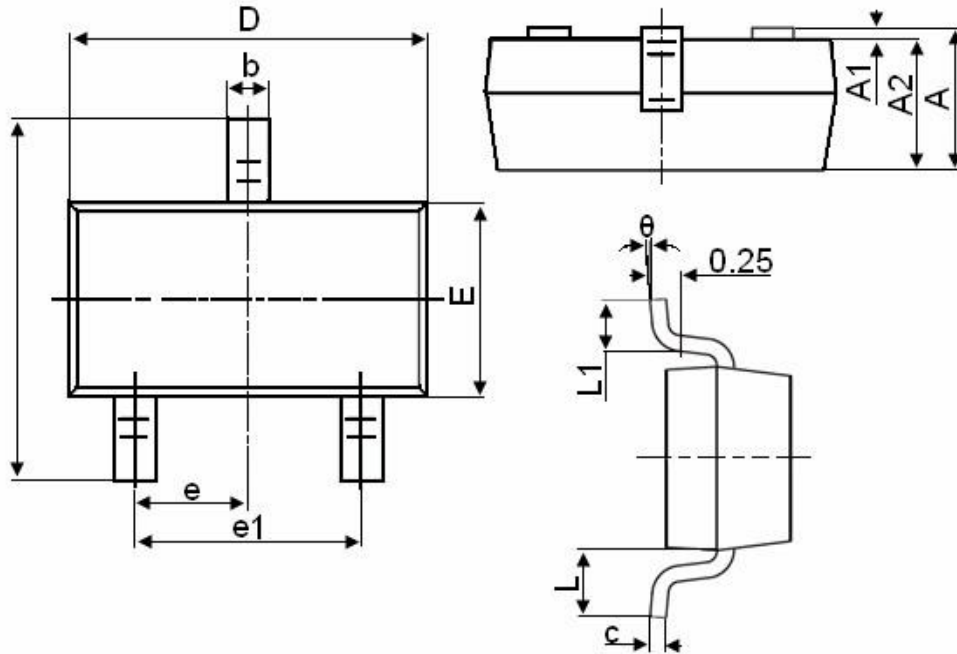


**Figure 10: Maximum Continuous Drain Current vs. Case Temperature**



**Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case**

**Package Mechanical Data-SOT23-XC-Single**



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°

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**-20V P-Channel Enhancement Mode MOSFET**

<b>Edition</b>	<b>Date</b>	<b>Change</b>
Rve1.0	2020/12/20	Initial release

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